



## Structural Health Monitoring: Latest Applications and Data Analysis, 2nd Edition

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Deadline for manuscript submissions:

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### Message from the Guest Editors

This Special Issue is devoted to Structural Health Monitoring (SHM). SHM techniques encompass all commonly used technical diagnostics and non-destructive testing methods, including electromagnetic, high-frequency, thermovision, radiography, ultrasound, and others. Each of the aforementioned methods presents unique issues, not just in terms of measurement methodology, but data processing as well. As a result, the processing of signals or images for the needs of qualitative and quantitative assessment of the structures under examination is also particularly intriguing in this context.

We invite scientists working in the broad field of technical diagnostics and nondestructive testing to submit original work on any of the above-mentioned themes. All types of research are welcome, including theoretical and experimental studies, as well as comprehensive reviews and surveys.





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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